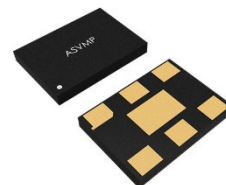


Description

The Abracon ASVMP series is a programmable MEMS oscillator, with a continuous operating power supply ranging from 2.25V to 3.6V. This series features low power consumption, a wide frequency range, excellent phase noise, tight stabilities, and short lead times for industrial, consumer, and other applications. The ASVMP series comes in a 7.0 x 5.0 mm compact package with CMOS, HCSL, LVDS, or LVPECL output logic.



Features

- Low Power Consumption for high-speed communication
- Exceptional Stability Over Temp. at -40 to +85°C, ± 10 ppm
- Extended Operating Temperature at -55 to +125°C, ± 25 ppm
- MIL-STD-883 shock and vibration compliant
- Durable QFN Plastic Compact Packaging
- Enable or Disable Tri-state function
- Low jitter (Period jitter RMS and Phase jitter RMS)
- High power supply noise reduction, -50dBc
- [REACH/RoHS II Compliant](#) | [MSL Level 1](#)

Applications

- Storage Area Networks (SATA, SAS, Fiber Channel)
- Passive Optical Networks (EPON, 10G-EPON, GPON, 10G-PON)
- Ethernet (1G, 10GBASE-T, /KR/LR/SR, FCoE)
- PCI Express
- Display port

Key Electrical Specifications – Continuous Vdd: 2.5V - 0.25V to 3.3V + 0.3V

Parameters		Min.	Typ.	Max.	Units	Notes
Frequency Range	CMOS	2.3000		170.0000	MHz	-20 ~ +70°C -40 ~ +85°C
	CMOS	3.3000		170.0000		-40 ~ +105°C -55 ~ +125°C
	LVPECL	2.3000		460.0000		-20 ~ +70°C -40 ~ +85°C -40 ~ +105°C
	LVDS	2.3000		460.0000		-20 ~ +70°C -40 ~ +85°C -40 ~ +105°C
	HCSL	2.3000		460.0000		-20 ~ +70°C -40 ~ +85°C -40 ~ +105°C
Operating Temperature		-20		+70	°C	See options
Storage Temperature		-55		+150	°C	
Overall Frequency Stability ^[Note 1]		-50		+50	ppm	See options
Supply Voltage (Vdd)		+2.25		+3.6	V	
Startup Time				5	ms	
Enable Time				20	ns	STD (Tri-state)

Key Electrical Specifications Cont. - CMOS, LVPECL, LVDS, and HCSL

Parameters	Min.	Typ.	Max.	Units	Notes
Disable Time			5	ns	
Disable Current		20	22	mA	STD (Tri-state)
Tri-state Function (Enable/Disable)	“1” ($V_{IH} \geq 0.75 \cdot V_{DD}$) or Open: Oscillation “0” ($V_{IL} < 0.25 \cdot V_{DD}$): Hi Z			V	40k Ω pull-up resistor embedded
Aging	-5.0		+5.0	ppm	First year

Note 1: Includes post reflow frequency accuracy, temperature stability, load pulling and power supply variation.

Key Electrical Specifications CMOS

Parameters		Min.	Typ.	Max.	Units	Notes
Supply current (I_{DD})			31	35	mA	CL=15pF, 125MHz
Output Logic Level	V_{OH}	$0.9 \cdot V_{DD}$			V	$I = \pm 6mA$
	V_{OL}			$0.1 \cdot V_{DD}$	V	
Rise Time	T_r		1.1	2.0	ns	CL=15pF 20% to 80%
Fall Time	T_f		1.3	2.0	ns	
Duty Cycle		45		55	%	
Integrated phase Jitter (J_{PH})			0.30	2	ps	200kHz~20MHz@125MHz
			0.38	2		100kHz~20MHz@125MHz
			1.70	2		12kHz ~ 20MHz@125MHz
Period Jitter RMS (J_{PER})			3.0		ps	

Key Electrical Specifications- LVPECL

Parameters		Min.	Typ.	Max.	Units	Notes
Supply Current (I_{dd})			56.5	58	mA	RL=50Ω
Output Logic Level	V_{OH}	$V_{dd}-1.08$			V	RL=50Ω
	V_{OL}			$V_{dd}-1.55$	V	
Peak to Peak Output Swing			800		mV	Single ended
Rise Time	T_r		250		ps	RL=50Ω, CL=0pF 20% to 80%
Fall Time	T_f		250			
Duty Cycle			48	52	%	Differential
Integrated phase Jitter (J_{PH})			0.25	2	ps	200kHz~20MHz@156.25MHz
			0.38	2		100kHz~20MHz@156.25MHz
			1.70	2		12kHz ~ 20MHz@156.25MHz
Period Jitter RMS (J_{PER})			2.5		ps	

Key Electrical Specifications LVDS

Parameters		Min.	Typ.	Max.	Units	Notes
Supply current (I_{dd})			29	32	mA	RL=100Ω
Output Offset Voltage (V_{os})		1.125		1.4	V	RL=100Ω differential
Delta Offset Voltage (ΔV_{os})				50	mV	
Peak to Peak Output Swing (V_{pp})			350		mV	Single ended
Rise Time	T_r		200		ps	RL=50Ω, CL=2pF 20% to 80%
Fall Time	T_f		200			
Duty Cycle		48		52	%	Differential
Integrated phase Jitter (J_{PH})			0.28	2	ps	200kHz~20MHz@156.25MHz
			0.40	2		100kHz~20MHz@156.25MHz
			1.70	2		12kHz ~ 20MHz@156.25MHz
Period Jitter RMS (J_{PER})			2.5		ps	

Key Electrical Specifications HCSL

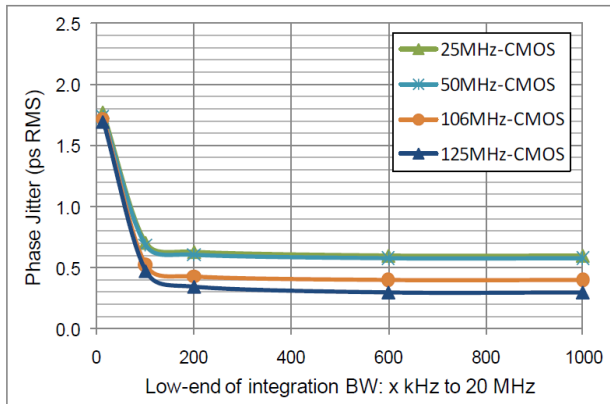
Parameters		Min.	Typ.	Max.	Units	Notes
Supply Current (I _{dd})			40	42	mA	RL=50Ω
Output Logic Level	V _{OH}	0.725			V	RL=50Ω
	V _{OL}			0.1	V	
Peak to Peak Output Swing (V _{pp})			750		mV	Single ended
Rise Time	T _r	200		400	ps	RL=50Ω, CL=2pF 20% to 80%
Fall Time	T _f	200		400		
Duty Cycle		48		52	%	Differential
Integrated Phase Jitter (J _{PH})			0.25	2	ps	200kHz ~ 20MHz@156.25MHz
			0.37	2		100kHz ~ 20MHz@156.25MHz
			1.70	2		12kHz ~ 20MHz@156.25MHz
Period Jitter RMS (J _{PER})			2.5		ps	

Absolute Maximum Ratings

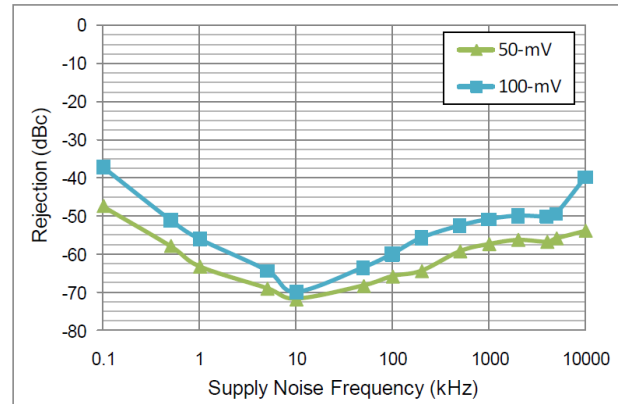
Item	Min.	Max.	Units
Supply voltage	-0.3	+4.0	V
Input voltage	-0.3	V _{dd} +0.3	V
Junction Temp.		+150	°C
Storage Temp.	-55	+150	°C
Soldering Temp.		+260	°C
ESD			
HBM		4,000	V
MM		400	
CDM		1,500	

Nominal Performance Parameters (Unless specified otherwise: T=25° C, VDD=3.3 V)

CMOS OUTPUT

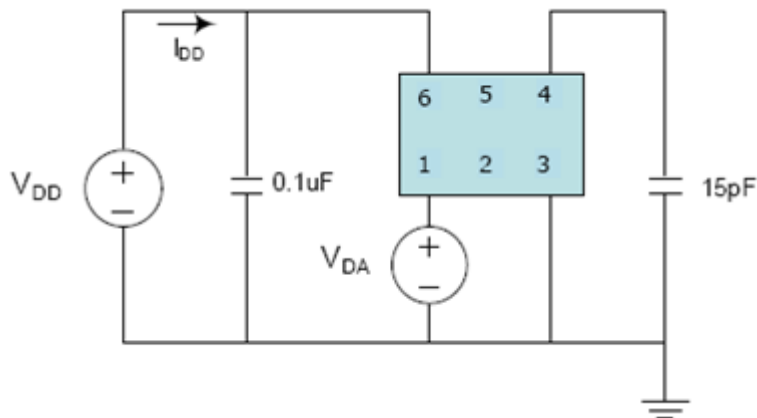


Phase jitter (integrated phase noise)

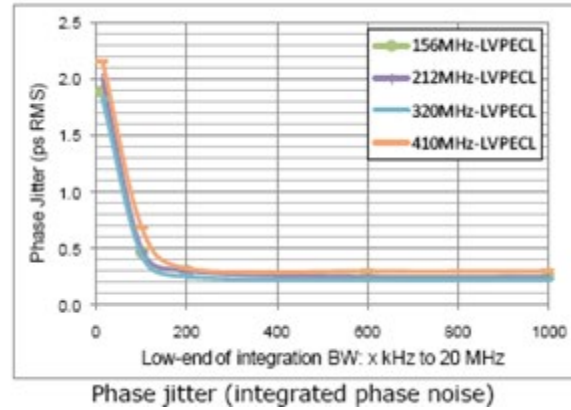
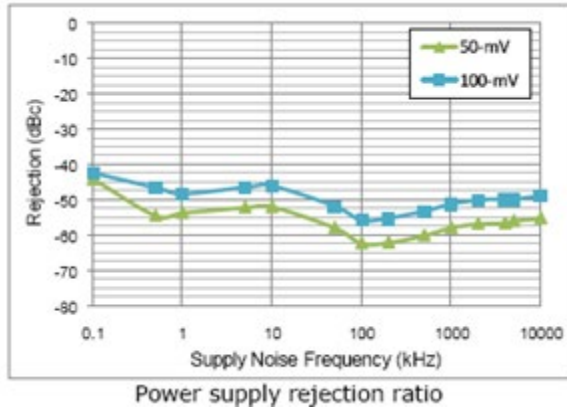


Power supply rejection ratio

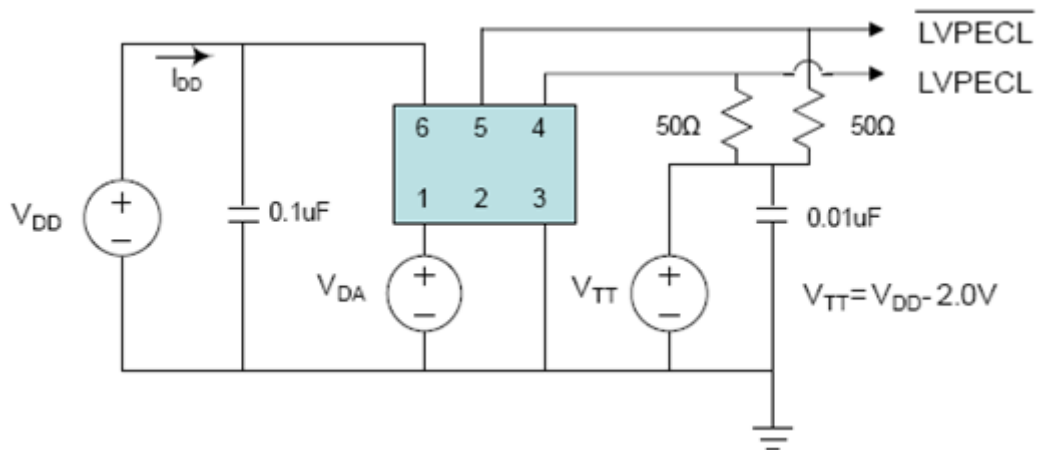
Test Circuit



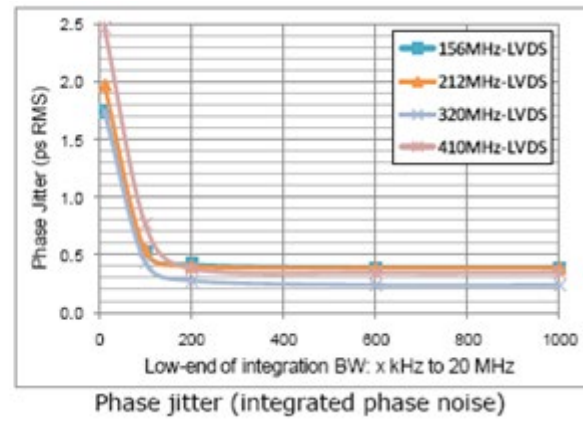
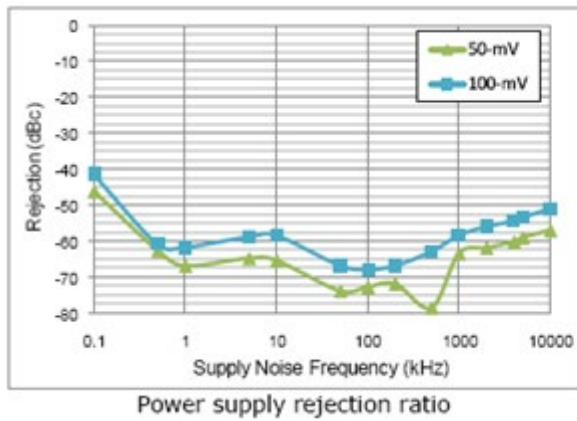
LVPECL OUTPUT



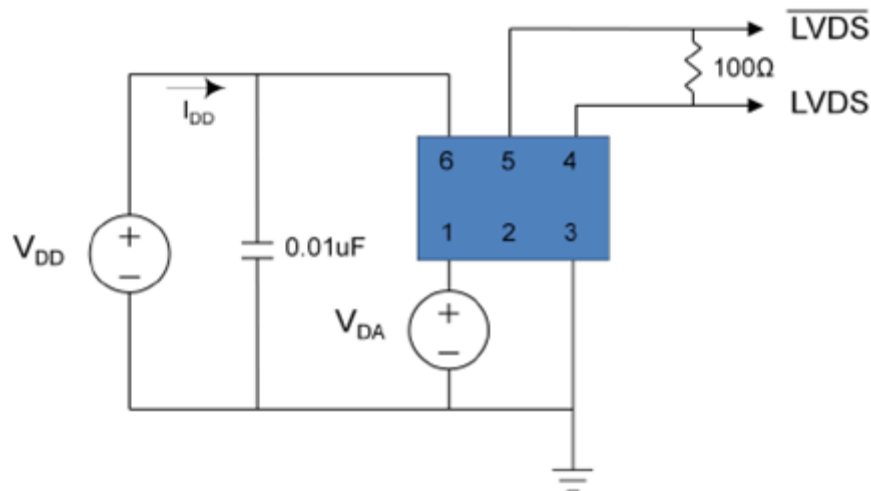
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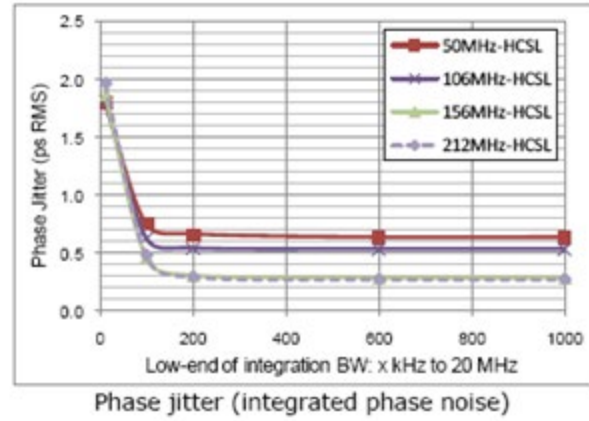
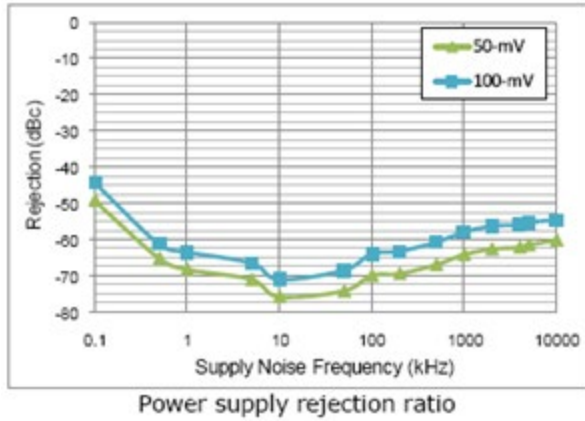
LVDS OUTPUT



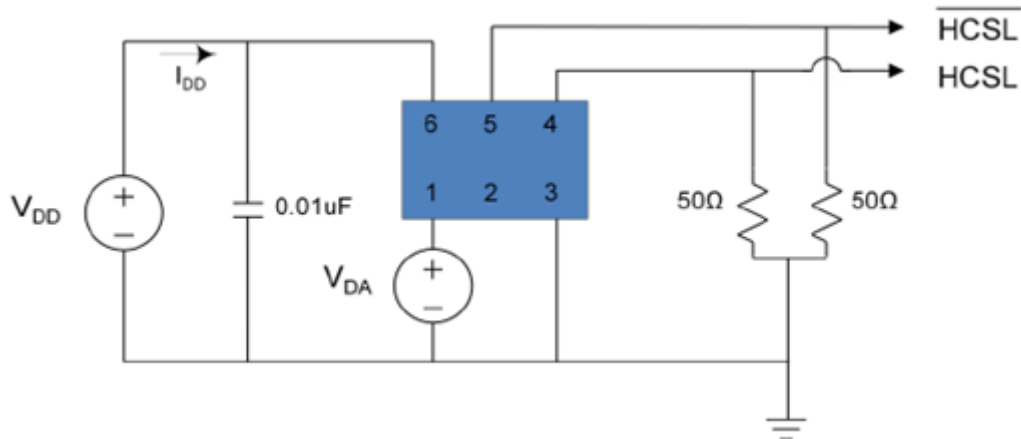
Test Circuit



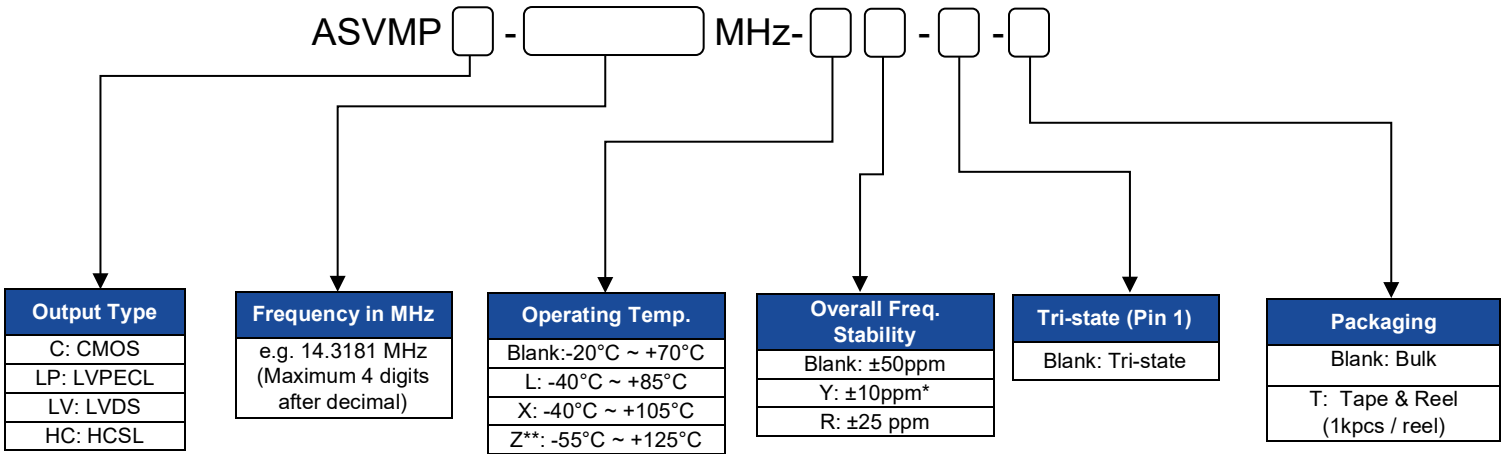
HCSL OUTPUT



Test Circuit

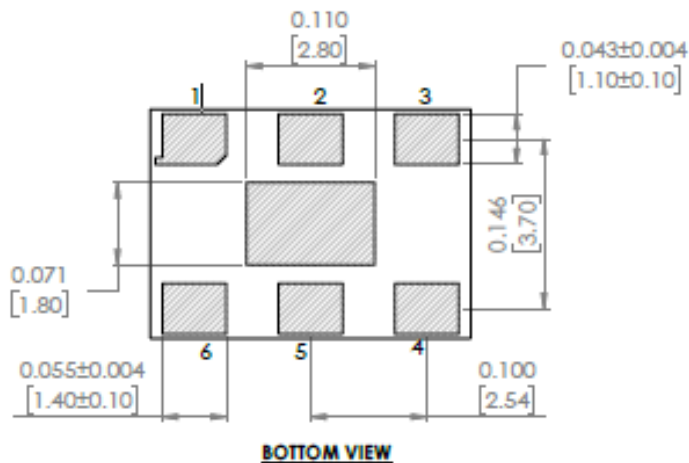
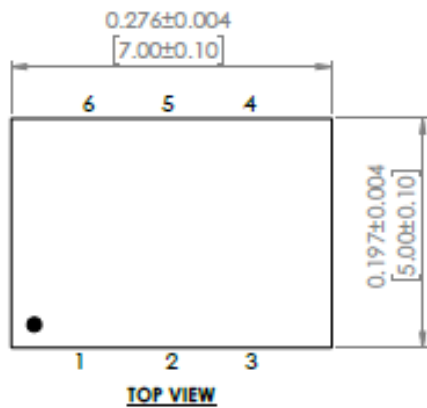


Option and Part Identification (left blank if standard)



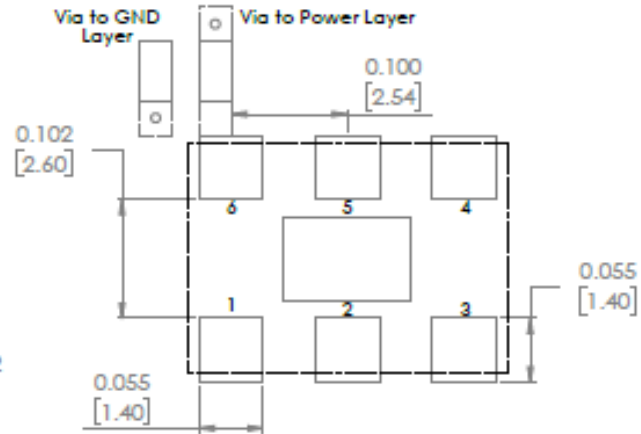
* Temp option L, X or -20°C ~ +70°C, only
** CMOS output only

Mechanical Dimensions

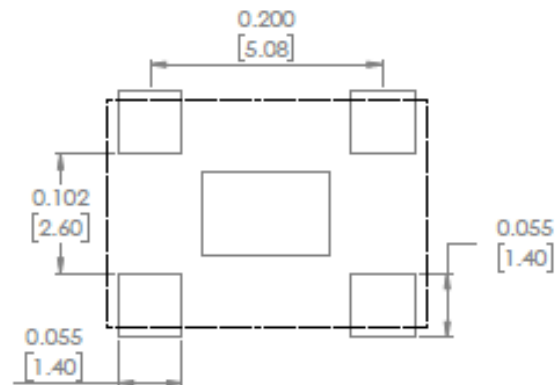


CENTER PAD: NC/GND

Recommended Land Pattern FOR LVPECL, LVDS, HCSL



Recommended Land Pattern FOR CMOS

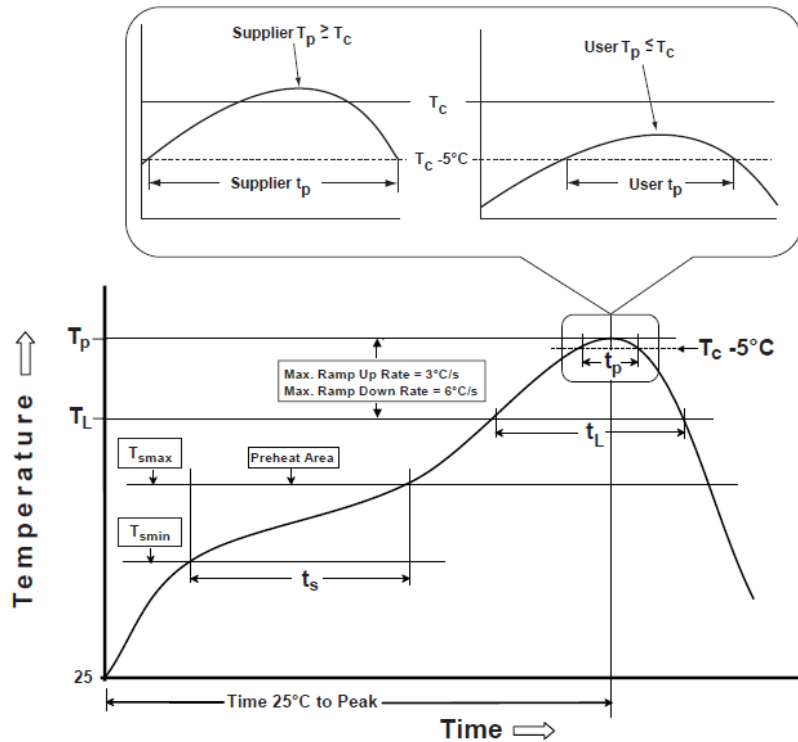


Note: Recommended using an approximately 0.01µF bypass capacitor between PIN 6 and PIN 3

Dimensions: Inches[mm]

Pin #	Function
1	Tri-State
2	NC
3	GND
4	Output
5	NC (CMOS) Output (LVPECL, LVDS, HCSL)
6	Vdd

Reflow Profile [JEDEC J-STD-020]


Table 1
**SnPb Eutectic Process
Classification Temperatures (T_c)**

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2
**Pb-Free Process
Classification Temperatures (T_c)**

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

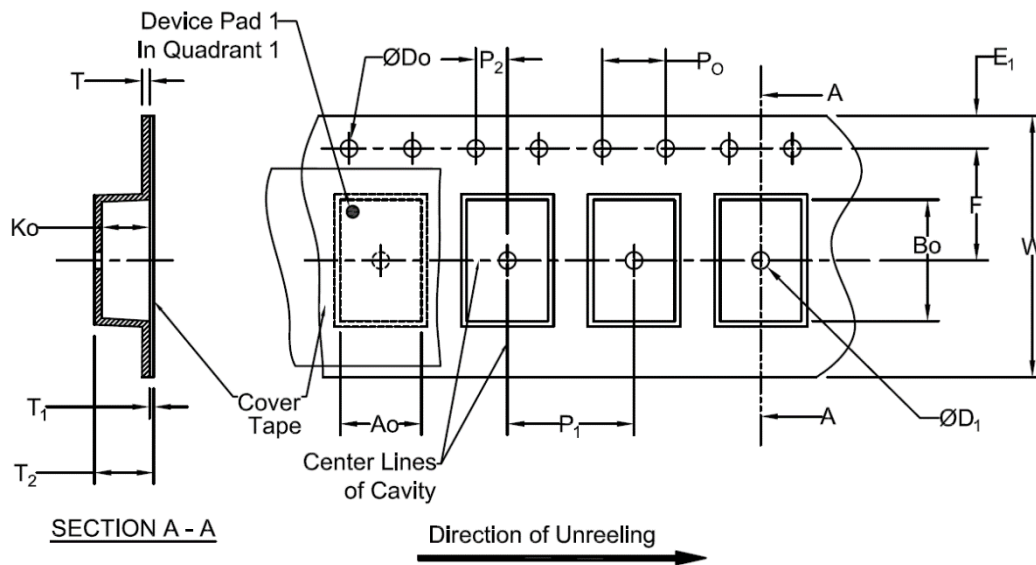
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T_{smin})	100°C	150°C
Temperature maximum (T_{smax})	150°C	200°C
Time (T_{smin} to T_{smax}) (t_s)	60 - 120 sec.	60 - 120 sec.
Average ramp-up rate (T_{smax} to T_p)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60 - 150 sec.	60 - 150 sec.
Peak package body temperature (T_p)*	see Table 1	see Table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20 sec.	30 sec.
Ramp-down rate (T_p to T_{smax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

*Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

**Tolerance for time at peak profile temperature (t_p) is defined as supplier minimum and a user maximum.

Packaging

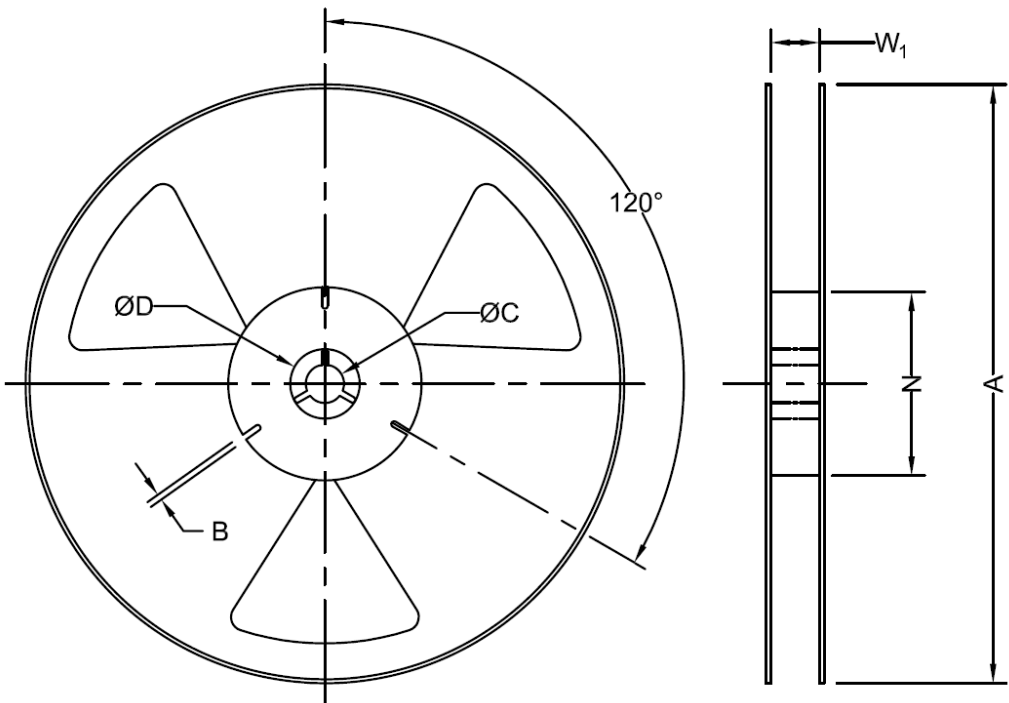
T: 1,000pcs/reel (D=180mm)



Tape Specifications (mm)							
Width	Ao	Bo	Do	D ₁ (Min)	E ₁	F	Ko
16mm	*	*	1.5+0.1/-0.0	1.0	1.75±0.1	7.5±0.10	*
Width	P1	P2	P0	T (Max)	T1 (Max)	T2 (Max)	W (Max)
16mm	8.0±0.1	2.0±0.1	4.0±0.1	0.6	0.1	8.0	16.3

***Note: Compliant to EIA-481**

Dimensions: mm



Reel Specifications (mm)							
Width	Qty/Reel	A (Nom)	B (Min)	C (Min)	D (Min)	N (Min)	*W ₁
16mm	1000	178	1.5	13.0+0.5/-0.2	20.2	50	16.4+2.0/-0.0

***Note: Measured at Hub**

Dimension: mm